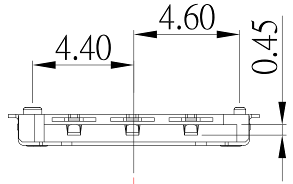
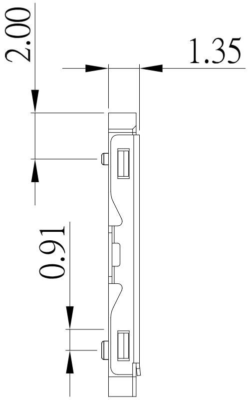
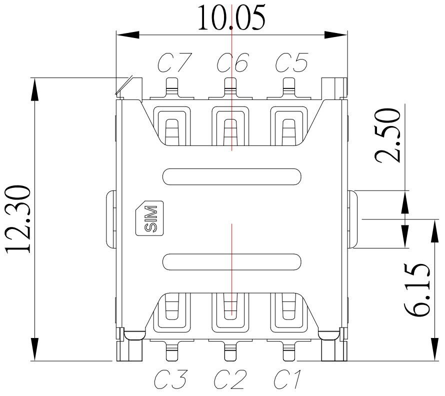
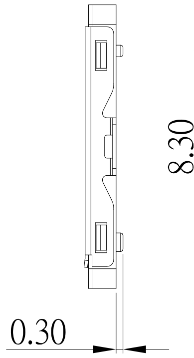
SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

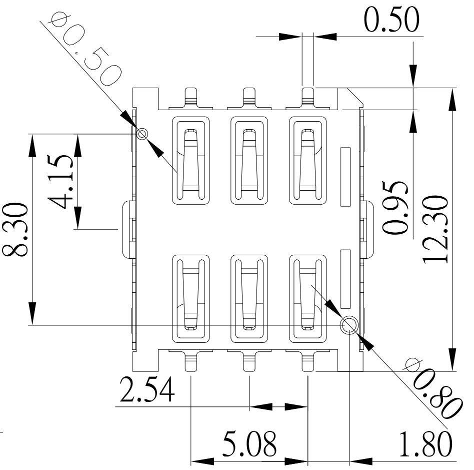
RoHS Compliant

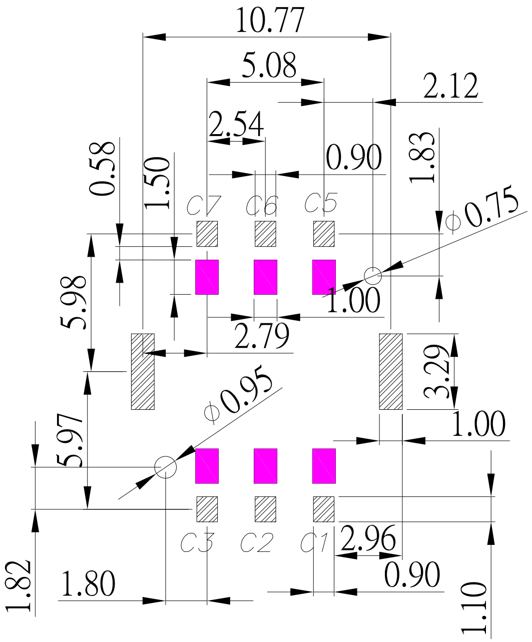








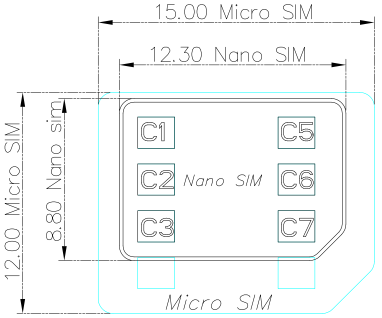


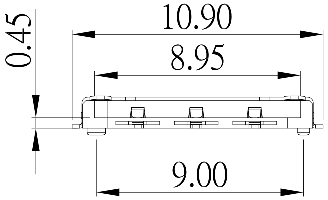


▬ PCB逼空位置

▨ RECOMMENDED PCB LAYOUT

P.C.B LAYOUT MOUNTING PATTERN





MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5 mA AC / DC MAX.
2. VOLTAGE RATING : 125V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40˚C TO +85˚C.
6. STORAGE TEMPERATURE RANGE : -40˚C TO +85˚C.

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	修正尺寸標示	Jack	020123
1	更新OPERATING TEMPERATURE RANGE	Jack	101221

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

DRAWN BY: Jack Lu	DATE 02/01/23	MAT'L		TITLE	CONNECTOR
CHECKED BY: Jacky Chen	DATE 02/01/23	FINISH		MODLE	Nano SIM CARD NO PUSH 1.35H 有柱
APPROVED BY: Tony Kao	DATE 02/01/23	SCALE	1 : 1	DWG NO.	NSIM-0201G06A-S267
		SHEET NO.	1 of 1	PART NO.	NSIM-0201G06A-S267

SIZE A4
VER R2

TOLERANCE UNLESS OTHERWISE STATED :		
Up to 5	± 0.2	
Above 5 ~ 15	± 0.3	
Above 15 ~ 30	± 0.4	
Above 30 ~ 50	± 0.5	
Angle	± 0.3˚	

3RD. ANGEL'S

UNITS MM